

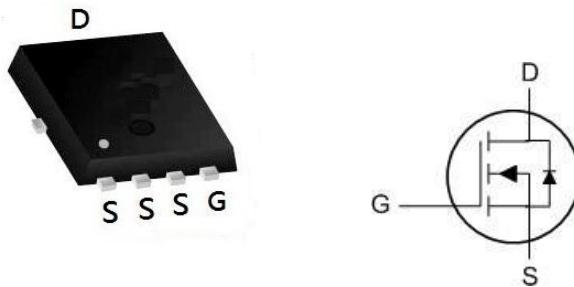
- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

**Product Summary**

BVDSS	RDS(ON)	ID
30V	3.0mΩ	120 A

**Description**

The XR120N03F is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications. The XR120N03F meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**PDFN5060-8L Pin Configuration****Absolute Maximum Ratings**

Symbol	Parameter	Rating		Units
		10s	Steady State	
V <sub>DS</sub>	Drain-Source Voltage	30		V
V <sub>GS</sub>	Gate-Source Voltage	±20		V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	120		A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	75		A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	384		A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	198		mJ
I <sub>AS</sub>	Avalanche Current	53.8		A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	62.5		W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	6	2.42	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175		°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 175		°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤ 10s)	---	25	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	2.4	°C/W

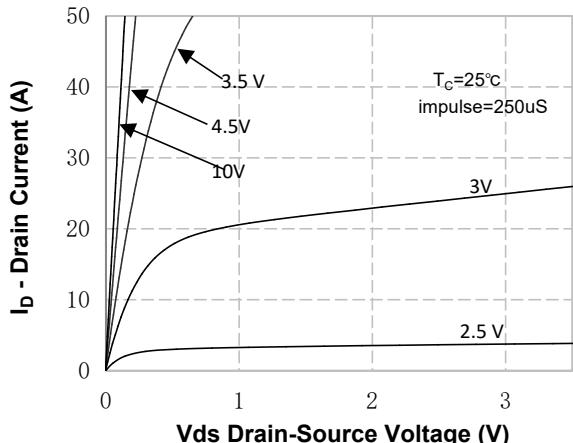
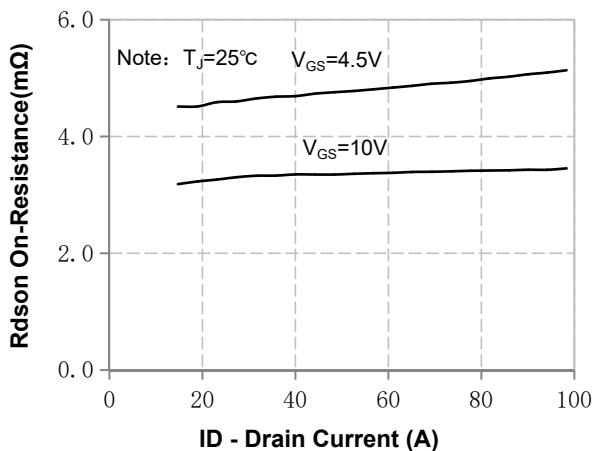
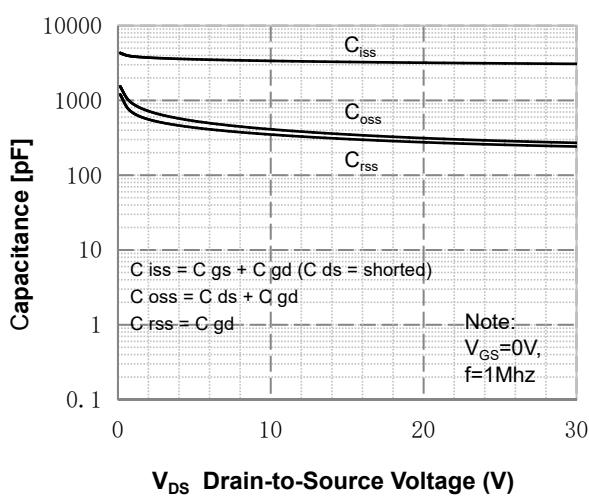
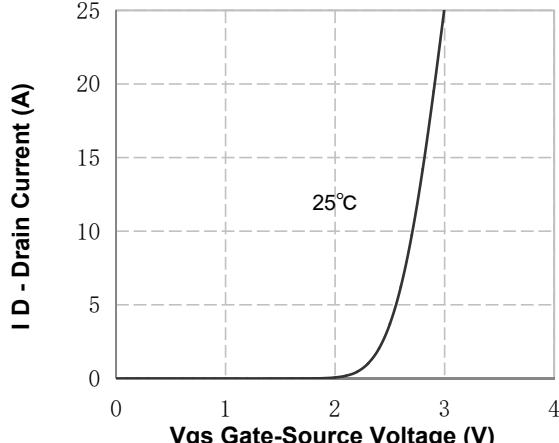
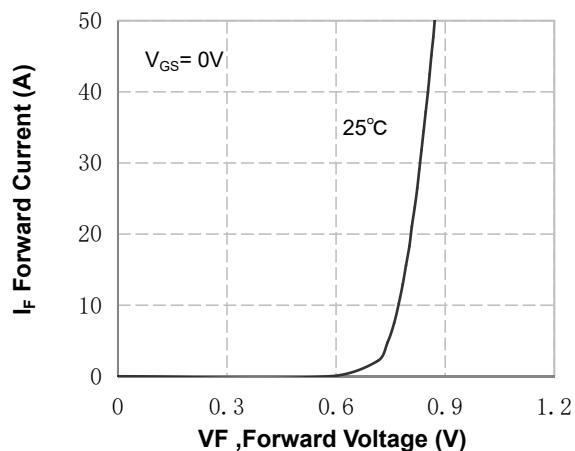
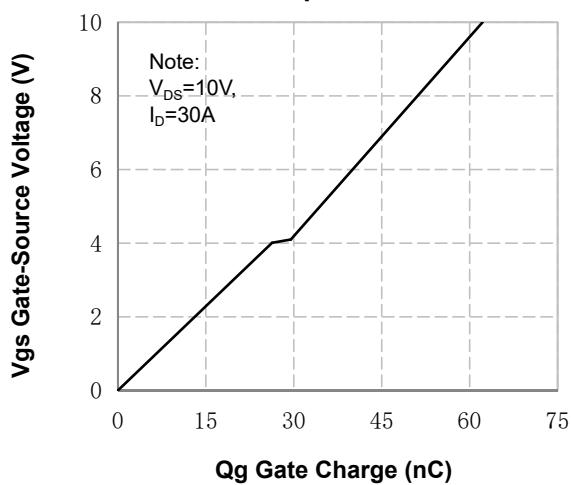
## N-Ch 30V Fast Switching MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

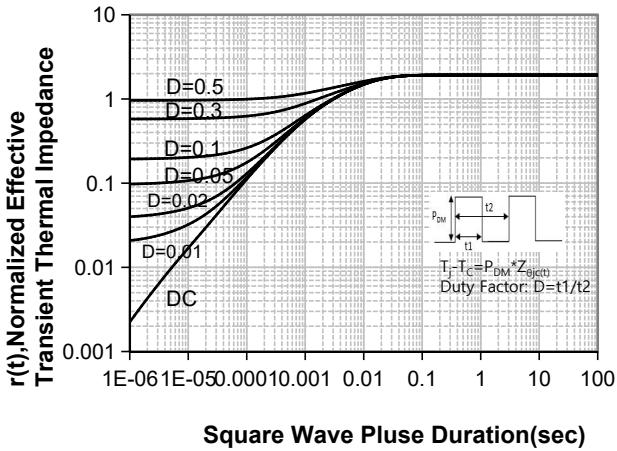
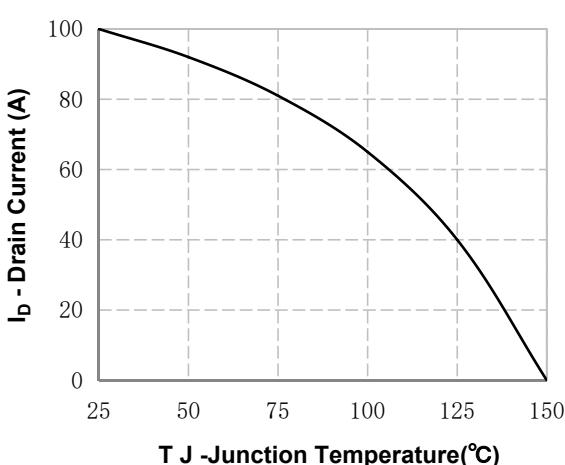
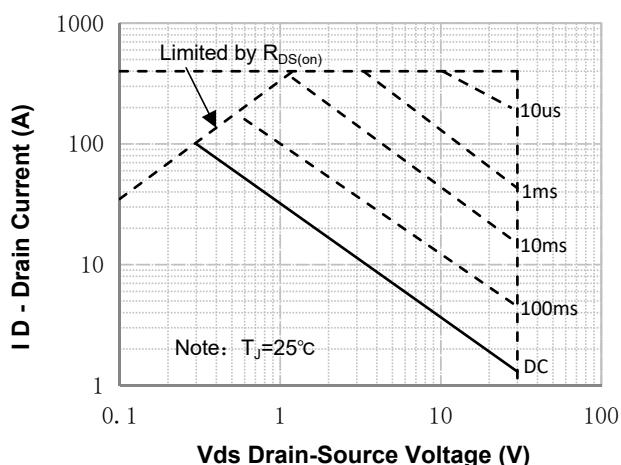
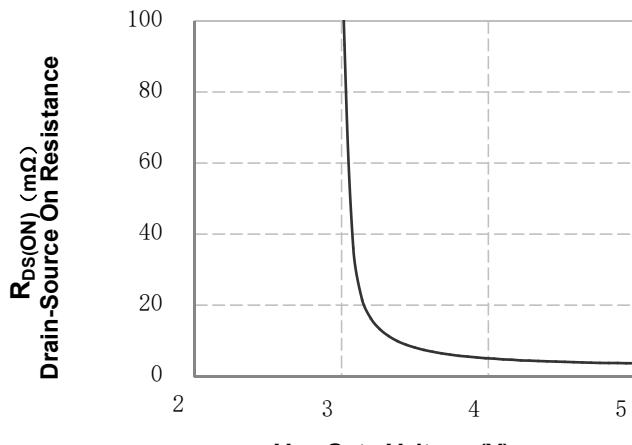
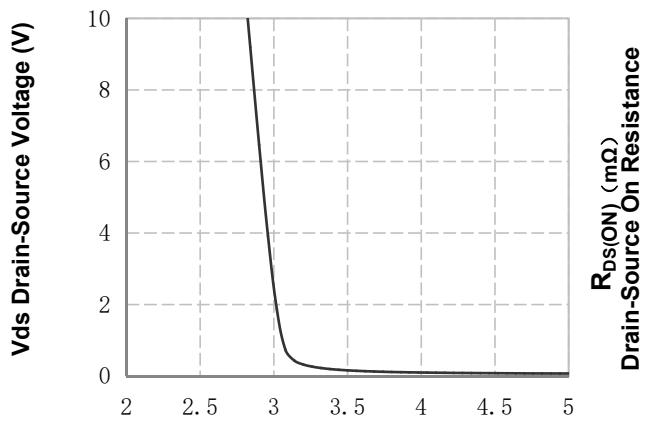
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{DS}}=250\mu\text{A}$	30	-	-	V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=24\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
		$\text{T}_J=85^\circ\text{C}$	-	-	30	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{DS}}=250\mu\text{A}$	1.4	1.7	2.5	V
$\text{I}_{\text{GSS}}$	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
$\text{R}_{\text{DS(ON)}}^{\text{d}}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{DS}}=20\text{A}$	-	3	3.8	$\text{m}\Omega$
		$\text{T}_J=125^\circ\text{C}$	-	4.4	-	
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{DS}}=15\text{A}$	-	4.0	5.5	
$\text{Gfs}$	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_{\text{DS}}=10\text{A}$	-	24.6	-	S
<b>Diode Characteristics</b>						
$\text{V}_{\text{SD}}^{\text{d}}$	Diode Forward Voltage	$\text{I}_{\text{SD}}=20\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	0.8	1.1	V
$\text{t}_{\text{rr}}$	Reverse Recovery Time	$\text{I}_{\text{DS}}=20\text{A}, \frac{d\text{I}_{\text{SD}}}{dt}=100\text{A}/\mu\text{s}$	-	35.6	-	ns
$\text{t}_{\text{a}}$	Charge Time		-	19.3	-	
$\text{t}_{\text{b}}$	Discharge Time		-	16.3	-	
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge		-	26	-	nC
<b>Dynamic Characteristics</b> <sup>e</sup>						
$\text{R}_G$	Gate Resistance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=0\text{V}, \text{F}=1\text{MHz}$	-	1	2	$\Omega$
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=15\text{V}, \text{Frequency}=1.0\text{MHz}$	-	2485	2971	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		-	850	-	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		-	85	-	
$\text{t}_{\text{d(ON)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=15\text{V}, \text{R}_L=15\Omega, \text{I}_{\text{DS}}=1\text{A}, \text{V}_{\text{GEN}}=10\text{V}, \text{R}_G=6\Omega$	-	12.4	23	ns
$\text{t}_{\text{r}}$	Turn-on Rise Time		-	9.5	18	
$\text{t}_{\text{d(OFF)}}$	Turn-off Delay Time		-	27.2	49	
$\text{t}_{\text{f}}$	Turn-off Fall Time		-	35.2	64	
<b>Gate Charge Characteristics</b> <sup>e</sup>						
$\text{Q}_{\text{g}}$	Total Gate Charge	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{DS}}=20\text{A}$	-	20.6	28.8	$\text{nC}$
$\text{Q}_{\text{g}}$	Total Gate Charge	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{DS}}=20\text{A}$	-	9.8	-	
$\text{Q}_{\text{gth}}$	Threshold Gate Charge		-	1.8	-	
$\text{Q}_{\text{gs}}$	Gate-Source Charge		-	3.8	-	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		-	3.7	-	

Note d : Pulse test ; pulse width $\leq300\mu\text{s}$ , duty cycle $\leq2\%$ .

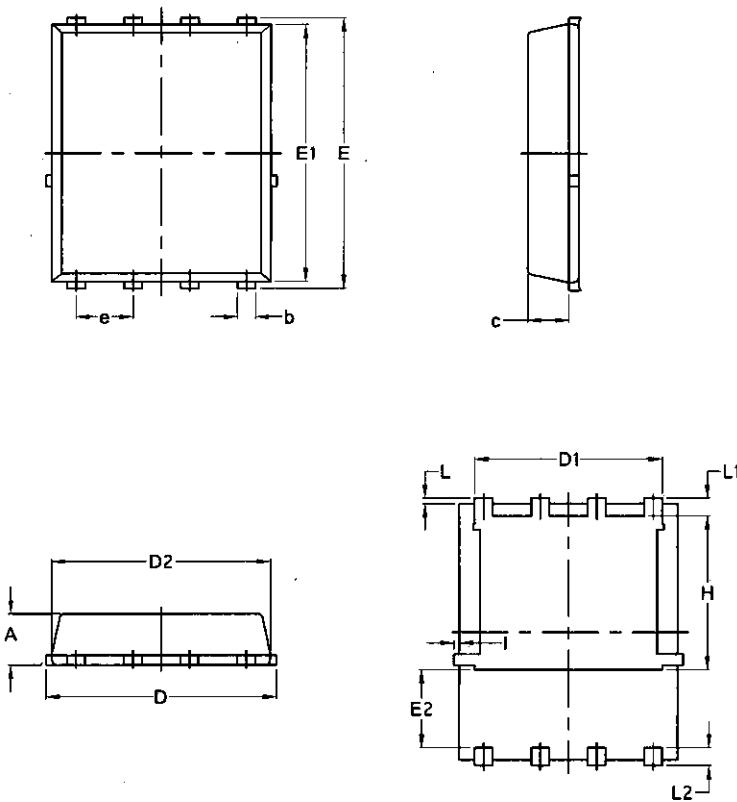
Note e : Guaranteed by design, not subject to production testing.

**N- Channel Typical Characteristics****Figure 1. On-Region Characteristics****Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage****Figure 5. Capacitance Characteristics****Figure 2. Transfer Characteristics****Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature****Figure 6. Gate Charge Characteristics**

## N- Channel Typical Characteristics (Continued)



## Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070